

SPECIFICATION AS AMENDED

Please replace the paragraph beginning at page 1, line ⁷~~9~~, with the following amended paragraph: 9/21/06
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A conventional substrate sawing process comprises an alignment for positioning a substrate strip so as to adjust the position of a saw machine and to arrange the position of the cutting tracks for substrate sawing. As shown in FIG. 1, a substrate strip 100 comprises a plurality of substrate areas 110 which are aligned along the longitudinal direction. ~~The substrate areas 110 have a~~ A plurality of alignment marks 111 enclose the substrate areas 110 for positioning a saw machine and cutting marks 112 ~~which~~ are provided for measuring or predetermining arrangement of the cutting tracks 101 of the substrate sawing process. After the saw machine is positioned and the cutting tracks 101 are arranged, the saw machine saws the substrate strip 100 along the cutting ~~track~~ tracks 101 which is are defined by the cutting marks 112, e.g. the cutting tracks 101 are imaginary lines created by two outermost cutting marks 112', shown in FIG. 1. However, in the prior art the saw machine ~~can choose~~ only chooses a set of one alignment mark 111, e.g. the outermost alignment marks 111' of the substrate strip 100 to define a reference point and utilizes the outermost cutting marks 112', located around the substrate areas 110, to predetermine the cutting tracks 101 in the first phase and the cutting tracks (not shown) in the second phase.

Please replace the paragraph beginning at page 1, line ²⁰~~24~~, with the following amended paragraph: 9/21/06
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The substrate strip 100 is packaged in high temperature circumstances and results in an expansion. When the substrate strip 100 returns to normal temperature, shrinkage in all dimensions occurs. However, each strip has variability which results in different amounts of shrinkage of the substrate strips 100 when returning from high temperature to normal temperature. Even if the substrate strips 100 are controlled in the same process and made of the same material, the shrinkage of the substrate strip